

AVIS-9000T

Automatic Vision Inspection System for Flip Chip BGA

Metal + Bump + SR inspection
by 2D surface inspection algorithm



Automatic
Vision Inspection System
for Flip Chip BGA

Advantages

- ▶ Metal + Bump + SR Inspection
- ▶ Highest Inspection Throughput
2.0~3.4sec./pc
- ▶ Highest Camera Working Resolution
5.5um/pixel
- ▶ Minimum Defect Size
down to 15um defect



Advanced Technology Inc.

AVIS-9000T

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Briefs of AVIS-9000T

- JEDEC tray handling system
- High Efficiency Cleaning Module (Ion-blower)
- Cylindrical Dome Lighting

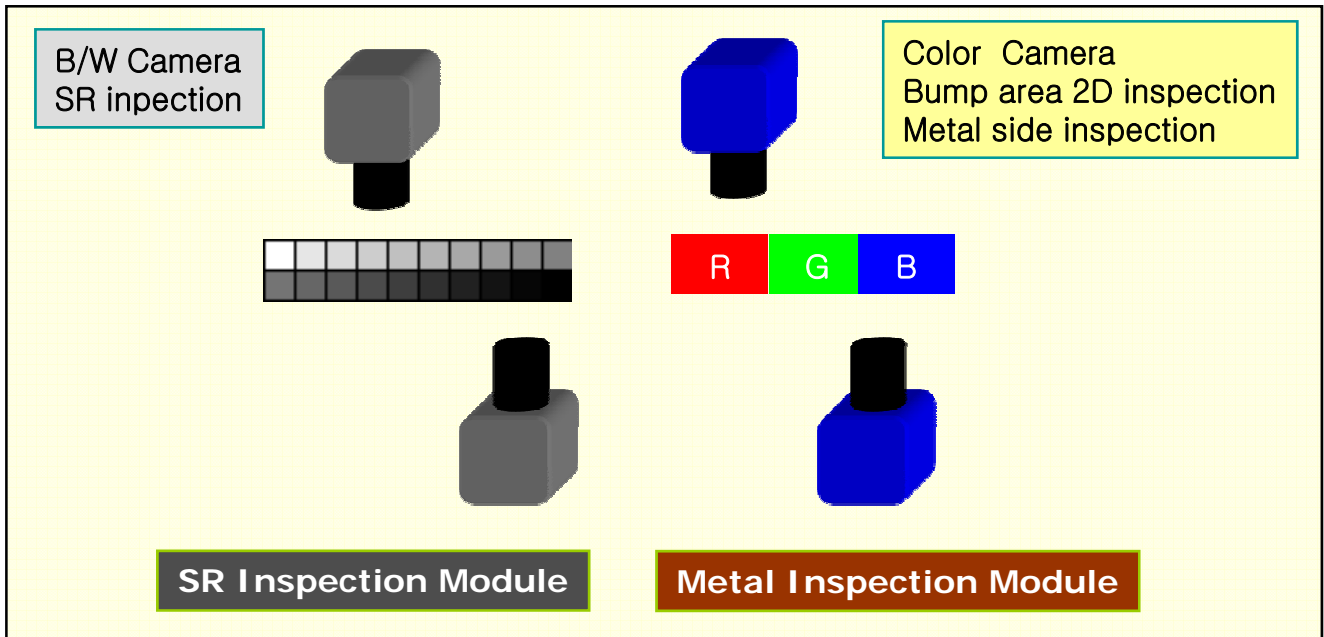


Image VS

Verification by color image

